

# 1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER PowerDI™323

#### **Features**

- Guard Ring Die Construction for Transient Protection
- High Surge Capability
- Lead Free Finish, RoHS Compliant (Note 1)
- "Green" Molding Compound (No Br, Sb)
- Qualified to AEC-Q101 Standards for High Reliability
- Ultra-Small Surface Mount Package

### **Mechanical Data**

- Case: PowerDI<sup>™</sup>323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Polarity: Cathode Band
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 @3
- Marking: Date Code & Type Code, See Page 3
- Type Code: 37
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)



**TOP VIEW** 



**BOTTOM VIEW** 

## **Maximum Ratings** @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	60	٧
RMS Reverse Voltage	V <sub>R(RMS)</sub>	42	V
Average Forward Current (See also figure 4)	I <sub>F(AV)</sub>	1.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	22	Α

#### Thermal Characteristics

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance Junction to Soldering Point	R <sub>0</sub> JS	_	6	°C/W
Thermal Resistance Junction to Ambient Air (Note 2)	$R_{ heta JA}$	173	_	°C/W
Thermal Resistance Junction to Ambient Air (Note 3)	$R_{ heta JA}$	125	_	°C/W
Operating Temperature Range	Tj	-65 to +150		°C
Storage Temperature Range	T <sub>STG</sub>	-65	°C	

Notes:

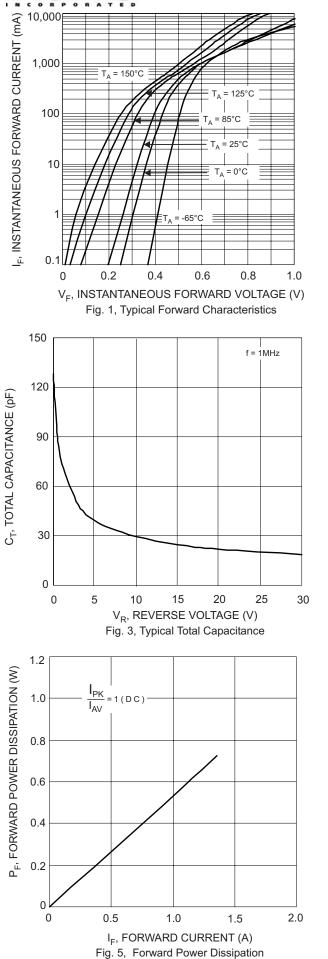
- 1. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.
- 2. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf. T<sub>A</sub> = 25°C.
- 3. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.  $T_A = 25^{\circ}C$ .

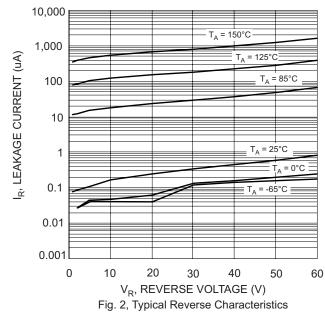
## Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V <sub>(BR)R</sub>	60	_	_	V	$I_R = 100 \mu A$
Forward Voltage	V <sub>F</sub>		0.40 0.55 —	0.45 0.58 0.64	V	I <sub>F</sub> = 0.1A I <sub>F</sub> = 0.7A I <sub>F</sub> = 1.0A
Leakage Current (Note 4)	I <sub>R</sub>	_	0.3 3	5 100	μА	V <sub>R</sub> = 5V, T <sub>A</sub> = 25°C V <sub>R</sub> = 60V, T <sub>A</sub> = 25°C
Total Capacitance (See also figure 3)	Ст	_	38	_	pF	V <sub>R</sub> = 10V, f = 1.0MHz

Notes: 4. Short duration pulse test to minimize self-heating effect.







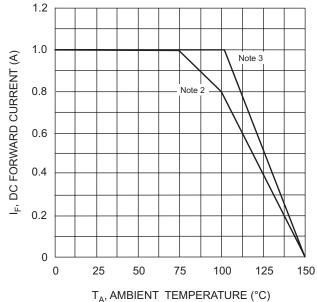
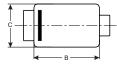


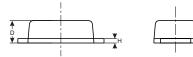
Fig. 4, DC Forward Current Derating 180 T<sub>A</sub>, DERATED AMBIENT TEMPERATURE (°C) Note 2 150 120 90 60 30 0 0 20 30 60 40 50 10  $V_R$ , DC REVERSE VOLTAGE (V)

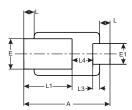
Fig. 6, Operating Temperature Derating



## **Package Outline Dimensions**

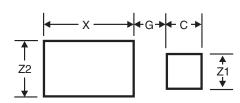






	Power	rDI <sup>™</sup> 323	
Dim	Min	Max	Тур
Α	2.40	2.60	2.50
В	1.85	1.95	1.90
С	1.20	1.30	1.25
D	0.60	0.70	0.65
Е	0.78	0.98	0.88
E1	0.50	0.70	0.60
Н	0.08	0.18	0.13
L	0.20	0.40	0.30
L1			1.40
L3			0.20
L4	0.40	0.80	0.60
All	Dimen	sions in	mm

# **Suggested Pad Layout**



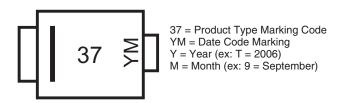
Dimensions	Value (in mm)
<b>Z</b> 1	0.8
<b>Z</b> 2	1.1
G	0.5
Х	2.0
С	0.8

# Ordering Information (Note 5)

Device	Packaging	Shipping		
PD3S160-7	PowerDI <sup>™</sup> 323	3,000/Tape & Reel		

Notes: 5. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012
Code	Т	U	V	W	X	Υ	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



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